

BPT-HPH36D-TRB

Description

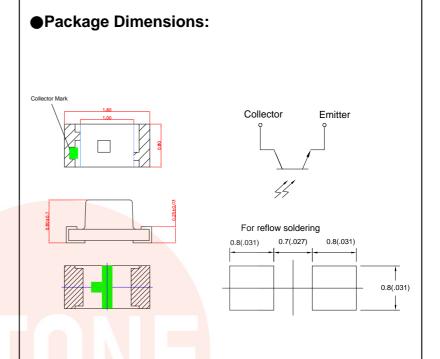
- 1. The BPT-HPH36D-TRB is a silicon NPN Phototransistor detector in a1.6x0.8x0.8mm SMD type package.
- 2. This product doesn't contain restriction Substance, comply ROHS standard.

Features:

- 1. Wide range of collector current.
- 2. Lend for high sensitivity.
- 3. Low cost plastic package.
- 4. Lens Appearance: Water Clear

Applications:

- 1. Smoke Detector
- 2. Automatic Control System
- Any design requiring sensitivity and stable characteristics.



NOTES:

- 1.All dimensions are in millimeters.
- 2.Tolerance is ±0.10mm unless otherwise specified.
- 3. Specifications are subject to change without notice.

■ Absolute Maximum Ratings(Ta=25°C)

Parameter	Symbol	Rating	Unit
Power Dissipation	Pd	100	mW
Emitter-Collector Breakdown Voltage	BV _{CEO}	50	V
Emitter-Collector Voltage	BV _{ECO}	5	V
Operating Temperature	Topr	-40°C ~85°C	-
Storage Temperature	Tstg	-40°C ~85°C	-
Soldering Temperature	Tsol	See Page6	-

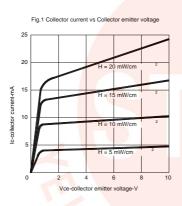


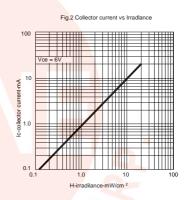
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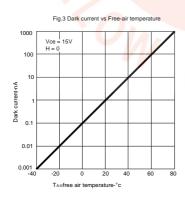
■ Electrical and optical characteristics(Ta=25°C)

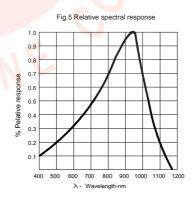
Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit
Spectrum Sensitivity	λ	I _F =50mA	500	-	1000	nm
Short Circuit Current	λр	I _F =50mA	-	940	-	nm
Collector Light Current	$I_{C(ON)}$	V _{CE} =5V, λp=940nm, H=1.0mw/cm ²	1.156	3.0	-	mA
Collector Dark Current	I_{CEO}	V _{CE} =20V			100	nA
Rise/Fall Time	Tr/Tf	V_{CE} =5V, Ic=1mA, R_L =1 $K\Omega$	ı	15/15	-	us
Viewing Angle	2θ _{1/2}	-	-	120	-	deg

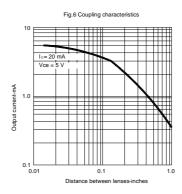
Typical Electro-Optical Characteristics Curves

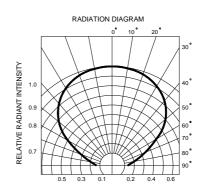






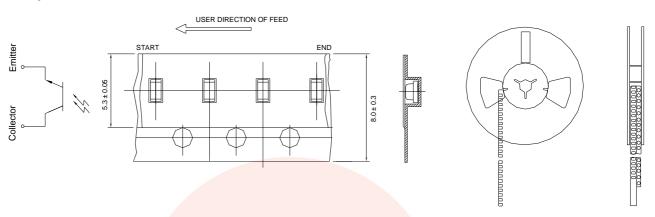




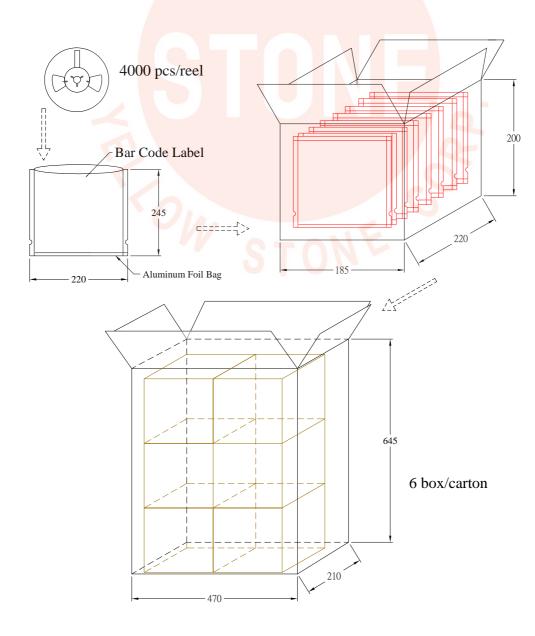




■ Tapping and packaging specifications(Units: mm) Quantity:4000PCS



●Package Method:(unit:mm) Vacuum





Bin Limits:

Collector Light Current Bin Limits($V_{CE}=5V$, H=1.0mw/cm², λ p=940nm)

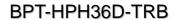
BIN CODE	I _{C(ON)} (m A)			
	Min	Max		
K	1.156	1.665		
L	1.665	2.398		
M	2.398	3.455		
N	3.455	4.976		
P	4.976	7.165		

Tolerance for each Bin limit is \pm 15 %



● BIN: X STONE

Collector Light Current Bin Code





Reliability Test

Classification	Test Item	Reference Standard	Test Conditions	Result
	Operation Life	MIL-STD-750D:1026 MIL-STD-883D:1005 JIS-C-7021 :B-1	Ta: Under room temperature Test time:1,000hrs IF=Product Recommended IF	0/32
Endurance		MIL-STD-202F:103B JIS-C-7021 :B-11	Ta:85±5°ℂ RH:90%-95% Test time:240hrs	0/32
	High Temperature Storage	MIL-STD-883:1008 JIS-C-7021 :B-10	Ta:100±5℃ Test time:1,000hrs	0/32
	Low Temperature Storage	JIS-C-7021 :B-11	Ta: -45±5℃ Test time=1,000hrs	0/32
Environmental Test V		MIL-STD-202F:107D MIL-STD-750D:1051 MIL-STD-883D:1010 JIS-C-7021 :A-2	Ta:-35±5°C ~25±5°C ~85±5°C ~25±5°C 30min 5min 30min 5min	0/32
	Thermal Shock	MIL-STD-202F:107D(1980) MIL-STD-750D:1051(95) MIL-STD-883D:1011(1 991)	Ta:-45±5°C ~+85±5°C 20min 20 min Time: 40min/cycle 10cycle	0/32
	Wetting balance	MIL-STD-883:2003 MIL-STD-202F:208D MIL-STD-883D:2003	Ta:230±5℃ Time:5±0.5s	0/32
	Solder Resistance	MIL-STD-202F:210A MIL-STD-883D:1011 JIS-C-7021 :A-1	Ta:260±10℃ Time:10±1s	0/32

Judgment criteria of failure for the reliability

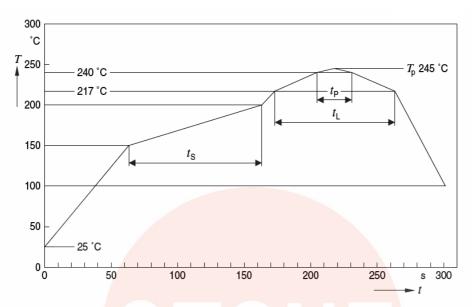
Measuring items	Symbol	Measuring conditions	Judgement criteria for failure
Forward voltage	$V_{F}(V)$	I _F =50mA	Initial Level*1.1
Reverse current	$I_R(uA)$	V _R =5V	Over U*2
Luminous intensity	lv (mcd)	I _F =50mA	Initial Level*0.7

Note: 1.U means the upper limit of specified characteristics.

2.Measurment shall be taken between 2 hours and after the test pieces have been returned to normal ambient conditions after completion of each test.



IR-Reflow Soldering



Profile Feature	Symbol Pb-F		-Free (SnAgCu) Assembly		Unit
		Minimum	Recommendation	Maximum	
Ramp-up rate to preheat ^{*)} 25 °C to 150 °C			2	3	K/s
Time t _S T _{Smin} to T _{Smax}	t _s	60	100	120	s
Ramp-up rate to peak ^{*)} T _{Smax} to T _P			2	3	K/s
Liquidus temperature	T _L		217		°C
Time above liquidus temperature	t		80	100	s
Peak temperature	T _P		245	260	°C
Time within 5 °C of the specified peak temperature T _P - 5 K	t _P	10	20	30	S
Ramp-down rate* T _P to 100 °C			3	6	K/s
Time 25 °C to T _P				480	S

All temperatures refer to the center of the package, measured on the top of the component

- 1. Avoid any external stress applied to the resin while the LEDs are at high temperature, especially during soldering.
- 2. Avoid rapid cooling or any excess vibration during temperature ramp-down process.
- Although the soldering condition is recommended above, soldering at the lowest possible temperature is feasible for the LEDs.

IRON Soldering

350°C Within 3 sec., One time only.

^{*} slope calculation DT/Dt: Dt max. 5 s; fulfillment for the whole T-range



Notes for designing:

Care must be taken to provide the current limiting resistor in the circuit so as to drive the LEDs within the rated figures. Also, caution should be taken not to overload LEDs with instantaneous voltage at the turning ON and OFF of the circuit.

When using the pulse drive care must be taken to keep the average current within the rated figures. Also, the circuit should be designed so as be subjected to reverse voltage when turning off the LEDs.

Storage:

In order to avoid the absorption of moisture, it is recommended to solder LEDs as soon as possible after unpacking the sealed envelope.

If the envelope is still packed, to store it in the environment as following:

- (1) Temperature : 5°C-30°C (41°F)Humidity : RH 60% Max.
- (2) After this bag is opened, devices that will be applied to infrared reflow, vapor-phase reflow, or equivalent soldering process must be: a. Completed within 168 hours.
- b. Stored at less than 30% RH.
- (3) Devices require baking before mounting, if: (2) a or (2) b is not met.
- (4) If baking is required, devices must be baked under below conditions: 48 hours at 60°C±3°C.

Package and Label of Products:

- (1) Package: Products are packed in one bag of 4000 pcs (one taping reel) and a label is attached on each bag.
- (2) Label:

